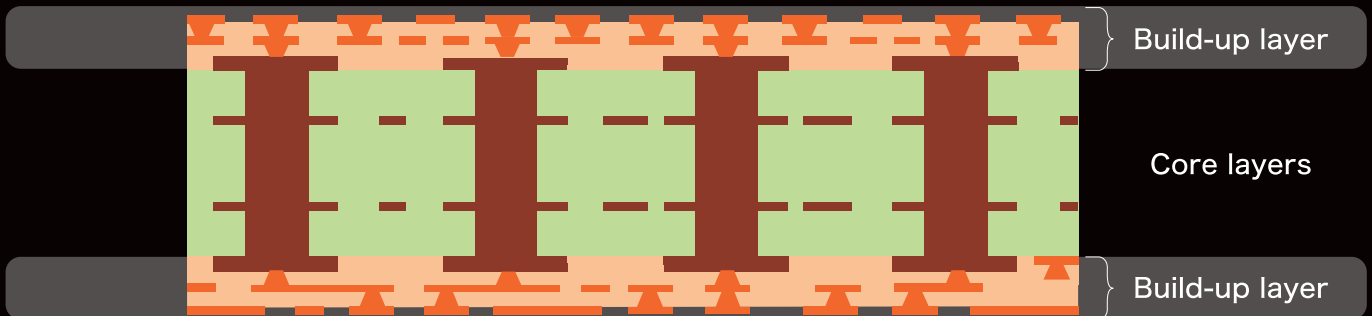


Acid copper plating additive
for high-current density, fine pattern via filling

TOP LUCINA NSV ADV

- ▶ Realize manufacture under 2 to 3A/dm² current density
- ▶ Can use for fine pattern designs (L/S=8/8μm)
- ▶ Best for pattern plating of build-up layers by high thickness uniformity



Excellent in pattern performance

Isolated circuits

60/100 20/100 10/100 8/100

■ : Isolated circuits
L/S=20/100μm

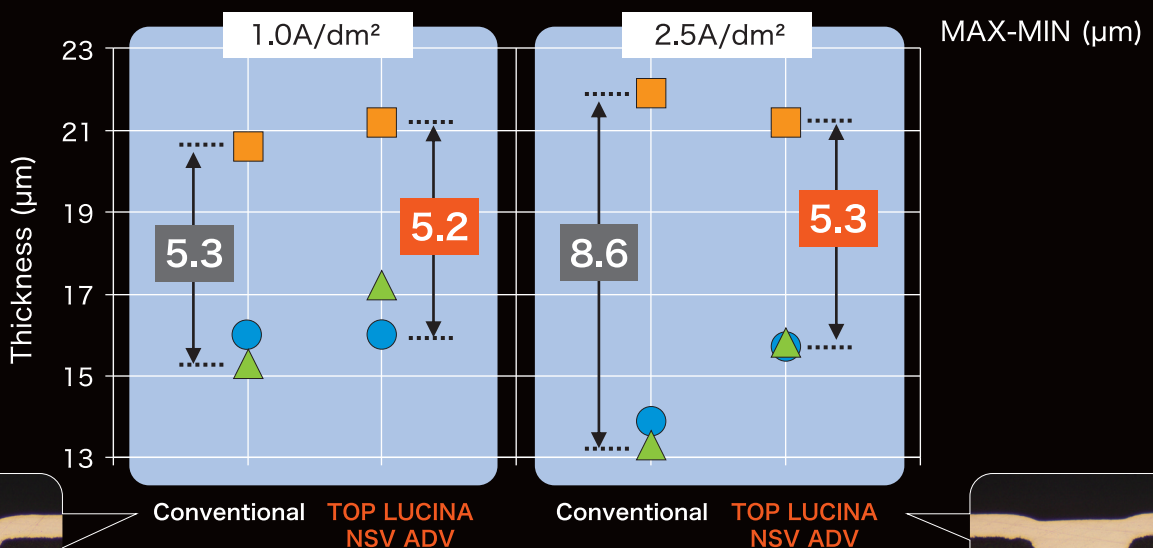
Dense circuits

60/60 20/20 10/10 8/8

● : Dense circuits
L/S=8/8μm

Coplanar circuits

▲ : Coplanar circuits
8μm



Can realize high-speed plating
with same quality